

A

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: SYUN-MING JANG AND MING-HSIN HUANG

For: HARD MASKING METHOD FOR FORMING PATTERNED OXYGEN CONTAINING PLASMA ETCHABLE LAYER

05/29/98  
ECS19  
Enclosed are:

2 sheets of formal drawing(s).

An assignment of the invention to Taiwan Semiconductor Manufacturing Company

An associate power of attorney

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 790.
TOTAL CLAIMS	16 -20=	0	x 22 =	\$ 0.
INDEP CLAIMS	2 -3=	0	x 82 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED		+ 260 =		
		SUB TOTAL		\$ 790.
		ASSIGNMENT		\$40.
		TOTAL		\$ 830.

Please charge my Deposit Account No. 19-0033 in the amount of \$ 830. A duplicate copy of this sheet is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

Any additional filing fees required under 37 CFR §1.16.

Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,  
*George O. Saile*  
GEORGE O. SAILE, REG. NO. 19,572